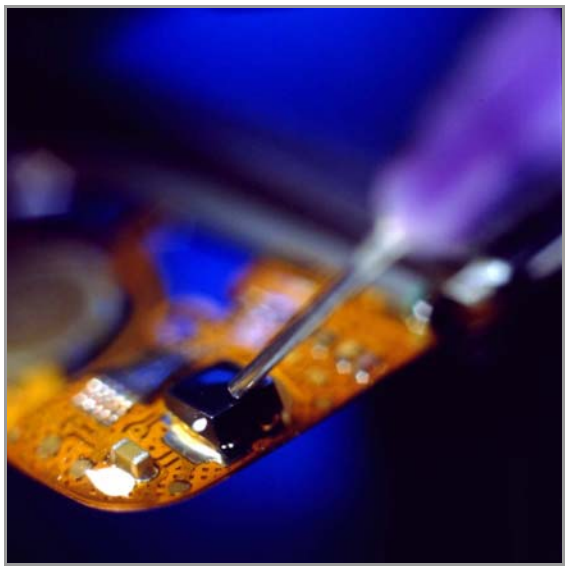
Chip Encapsulants

For Superior Protection on Flexible and Rigid Platforms

DYMAX 9000 Series UV/Visible light-curable encapsulants cure in seconds and are easily incorporated into automated systems for maximizing microelectronic assembly and protection speeds. These tough, flexible encapsulants have high ionic purity, resistance to humidity, and resistance to thermal shock to effectively protect components and improve their reliability. 9000 Series single-component encapsulants contain no sharp, abrasive mineral or glass fillers to abrade fine wires, and their combination of low T_g and low modulus means low stress. They have excellent adhesion to Polyimide, PET, flexible printed circuits, FR4, and ceramic boards and provide superior protection for glob top and chip-on-board applications. 9000 series encapsulants are ideal for encapsulating IC's in flex circuits. The encapsulants are available in a wide range of viscosities, from thin wicking to non-flowing gel.



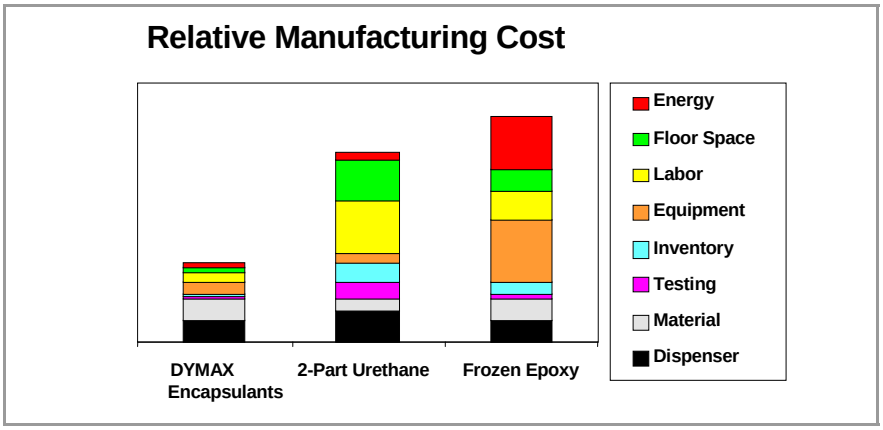
Clear UV-Curable Encapsulants

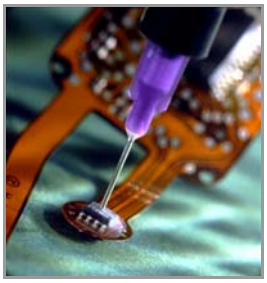
Feature	Benefit
▪ UV/Visible light cure in seconds	▪ Highest assembly throughput ▪ Minimal handling requirements
▪ 100% solvent free	▪ No VOCs ▪ High coverage
▪ High ionic purity ▪ Resistance to thermal shock ▪ Resistance to moisture ▪ Low stress under thermal cycle ▪ Electrically insulating	▪ Maximum post-assembly reliability
▪ Room-temperature storage	▪ Ease of storage ▪ Eliminate energy waste of refrigeration

Product	Features	Application	Durometer Hardness	Viscosity *(cP)*	Elongation at Break	Modulus of Elasticity
9001-E-v3.1	General purpose, medium viscosity encapsulant, good adhesion to flexible and rigid printed circuits	Chip Encapsulant	D45	4,500	150%	2,500 psi
9001-E-v3.5	Higher viscosity 9001-E Series encapsulant	Chip Encapsulant	D45	17,000	150%	2,500 psi
9001-E-v3.7	Thixotropic viscosity encapsulant	Dam or Thick Coatings	D45	50,000	150%	2,500 psi
9008	More flexible version of 9001-E-v3.1 for difficult substrates	Chip Encapsulant	A85	4,500	300%	2,000 psi

High Ionic Purity

Typical Ionic Content		
Extractable Chloride	<10 ppm	IC
Sodium	<10 ppm	ICP
Potassium	<10 ppm	AA
Fluoride	<10 ppm	IC



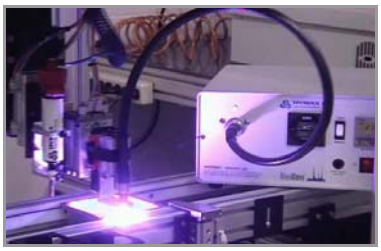


IC Kapton
Flex Circuit Encapsulant

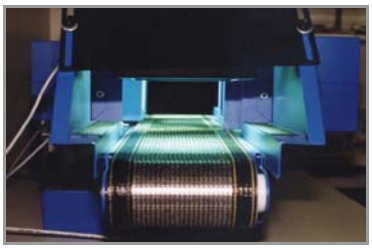
Glob Top and
Black Encapsulants

Curing Options for DYMAX Encapsulants

DYMAX encapsulants cure in seconds upon exposure to UV light, affording the fastest processing possible. Avoid processing bottlenecks by choosing an efficient and cost effective DYMAX encapsulant with a matched DYMAX UV light-curing system.



Automated DYMAX spot light-curing system mounted on a robotic dispenser



Cure large parts or arrays of parts under high-intensity conveyorized light-curing systems

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